	S	PECIFICATION					
宏致	女 霍	了 了 股 份 有 限	夏公司				
	桃	園縣中壢市東園路13號					
		13, Dongyuan Rd., Jhongli City					
Taoyuan County 320, Taiwan (R.O.C.) TEL: +886-3-463-2808 FAX: +886-3-463-1800							
<b>SPEC. NO.:</b> PS-516	92-XX	XXX-XXX REV	ISION: ]A				
PRODUCT NAME:	0.4 m	IM PITCH ZIF BACK-FLIP F	PC CONN.				
	SMT	R/A D/C TYPE					
<b>PRODUCT NO:</b>	5169	2 SERIES					
PREPARED:		CHECKED:	APPROVED:				
JAMESLEN.WANG RYAN.LIU K.HISATOMI							
DATE: DATE: DATE: DATE: 2016/10/05 DATE 2016/10/05							
2010/10/03							



#### TITLE: 0.4 MM PITCH ZIF BACK-FLIP FPC CONN RELEASE DATE: 2016/10/05 **REVISION:** A ECN No: ECN-1610012 PAGE: 2 OF 15 1 2 APPLICABLE DOCUMENTS ...... 4 3 4 5 6 7 8 CONNECTOR OPERATION ......10



#### TITLE: 0.4 MM PITCH ZIF BACK-FLIP FPC CONN

RELEASE DATE: 2016/10/05	REVISION: A	ECN No: ECN-1610012	PAGE: 3 OF 15

# 1 Revision History

Rev.	ECN #	Revision Description	Prepared	Date
0	ECN-1607346	ADD CONNECTOR OPERATION & RELEASE REV-O	JAMESLEN	2016.07.15
Α	ECN-1610012	ADD Working voltage	JAMESLEN	2016.10.05

	CONNECTORS		Aces P/N: 5	1692 series	
Т	ITLE: 0.4 MM PITCH ZIF	BACK-FLIP FPC	CONN		
REL	EASE DATE: 2016/10/05	REVISION: A		ECN No: ECN-1610012	PAGE: 4 OF 15
2	SCOPE This specification cov 1.0 mm above board			nd quality requiremen Flip FPC connector.	ts for 0.4 mm pitch
	ACES Part/Number :				
3	APPLICABLE DOC	UMENTS			
	EIA-364: ELECTRONI	CS INDUSTRIE	S ASSOCIA	TION	
4	REQUIREMENTS				
	4.1 Design and Constru	ction			
	applicable	product drawing	g.	on and physical dimension the standard depends o	
	4.2 Materials and Finish				
	Finish: ( ( ( 4.2.2 Housing: Th	a) Contact Area b) Under plate: c) Solder area: nermoplastic or	a: Refer to the Refer to the Refer to the Thermoplas	e drawing.	
	4.3 Ratings				
	4.3.1 Working volt 4.3.2 Voltage: 50 4.3.3 Current: 0.3 4.3.4 Operating Te	Volts AC (per p Amperes (per	in) pin)		
				2010	/10/31 TR-FM-73015L



#### TITLE: 0.4 MM PITCH ZIF BACK-FLIP FPC CONN

ECN No: ECN-1610012

# 5 Performance

# 5.1. Test Requirements and Procedures Summary

**REVISION:** A

ltem	Requirement	Standard				
	Product shall meet requirements of	Visual, dimensional and functional				
Examination of Product	applicable product drawing and	per applicable quality inspection				
	specification.	plan.				
	ELECTRICAL					
ltem	Requirement	Standard				
	•	Mate connectors, measure by dry				
Low Level	100 m $\Omega$ Max. per contact	circuit, 20mV Max., 100mA				
Contact Resistance		Max.				
		(EIA-364-23)				
		Unmated connectors, apply				
Insulation Resistance	1000 M Ω Min.	250 V DC between adjacent				
		terminals. applied for 1 min.				
		(EIA-364-21)				
		250 VAC Min. at sea level for 1				
Dielectric	No discharge, flashover or	minute.				
Withstanding Voltage	breakdown.	Test between adjacent contacts of				
withstanding voltage	Current leakage: 1 mA max.	unmated connectors.				
		(EIA-364-20)				
		Mate connector: measure the				
		temperature rise at rated current				
Tomporaturo rico	20°C Max Change allowed	until temperature stable. The				
Temperature rise	$30^{\circ}$ C Max. Change allowed	ambient condition is still air at $25^\circ$ C				
		(EIA-364-70,				
		METHOD1,CONDITION1)				



#### TITLE: 0.4 MM PITCH ZIF BACK-FLIP FPC CONN

RELEASE DATE: 2016/10/05

REVISION: A

ECN No: ECN-1610012

PAGE: 6 OF 15

ltom	MECHANICA	Stondard				
ltem	Requirement Standard					
Durability	20 cycles.	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of $25.4 \pm 3$ mm/min. (EIA-364-09)				
FPC Retention Force	Min. 0.1N/pin contact X pin contacts(initial)	A connector shall be soldered on a board and insert the actuator, pull the FPC at the speed rate of $25.4 \pm 3 \text{ mm/min.}$				
Terminal /Housing Retention Force	30 gf MIN.	Operation Speed : 25.4 $\pm$ 3 mm/minute. Measure the contact retention force with Tensile strength tester.				
Fitting Nail /Housing Retention Force	50 gf MIN.	Operation Speed : 25.4 $\pm$ 3 mm/minute. Measure the contact retention force with Tensile strength tester.				
Vibration	1 μs Max.	The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm (1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be traversed in approximately 1 minute. This motion shall be applied for 2 hours in each of three mutually perpendicular directions. (EIA-364-28 Condition I)				
Shock (Mechanical)	1 μs Max.	Subject mated connectors to 50 G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be 100mA maximum for all contacts. (EIA-364-27, test condition A)				



#### TITLE: 0.4 MM PITCH ZIF BACK-FLIP FPC CONN

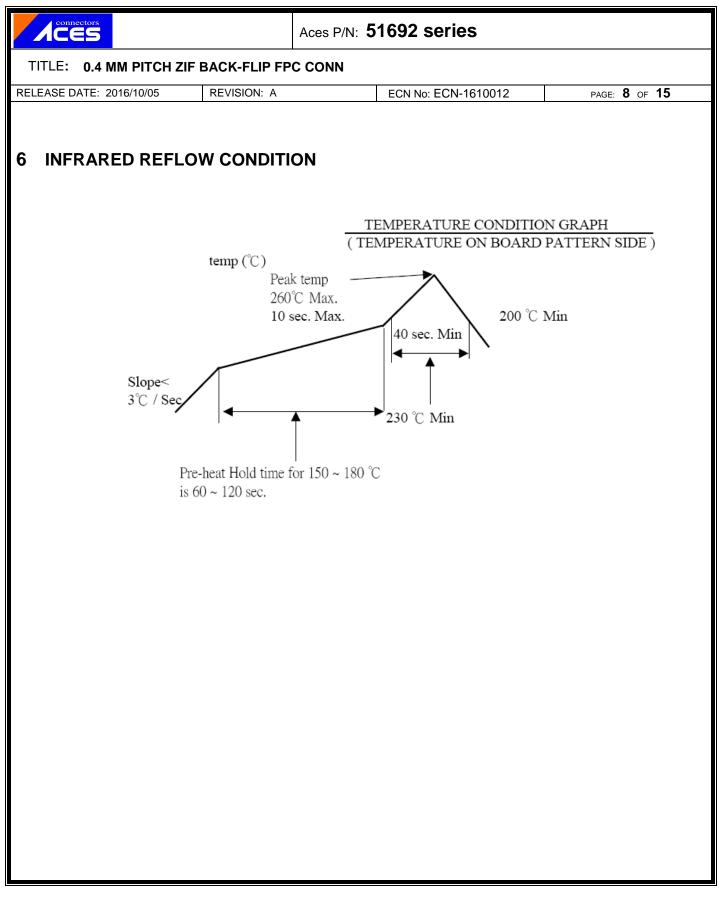
RELEASE DATE: 2016/10/05

REVISION: A

ECN No: ECN-1610012

	ENVIRONMENTA	
ltem	Requirement	Standard
Resistance to <b>Reflow</b> Soldering Heat	See Product Qualification and Test Sequence Group 9 (Lead Free)	Pre Heat:150℃~180℃, 60~120sec. Heat:230℃ Min., 40sec Min. Peak Temp.:260℃Max, 10sec Max.
Thermal Shok (with FPC mated)	See Product Qualification and Test Sequence Group 4	Mate module and subject to follow condition for 5 cycles.
Humidity (with FPC mated)	See Product Qualification and Test Sequence Group 4	Mated Connector 40℃, 90~95% RH, 120 hours. (EIA-364-31,Condition A, Method II)
Temperature life (with FPC mated)	See Product Qualification and Test Sequence Group 5	Subject mated connectors to temperature life at 85°C for 96 hours. (EIA-364-17, Test condition A)
Salt Spray (with FPC mated) (Only For Gold Plating)	See Product Qualification and Test Sequence Group 6	Subject mated/unmated connectors to 5% salt-solution concentration, 35°C (I) Gold flash for 8 hours (II) Gold plating 3 u" for 48 hours (III) Gold plating 5 u" for 96 hours (EIA-364-26)
Solder ability	Tin plating: Solder able area shall have minimum of 95% solder coverage. Gold plating: Solder able area shall have minimum of 75% solder coverage	And then into solder bath, Temperature at 245 ±5℃, for 4-5 sec. (EIA-364-52)
Hand Soldering Temperature Resistance	Appearance: No damage Sequence Group 10	T≧300℃, 5sec at least. T≧350℃, 3sec at least.

Note. Flowing Mixed Gas shell be conduct by customer request.





#### TITLE: 0.4 MM PITCH ZIF BACK-FLIP FPC CONN

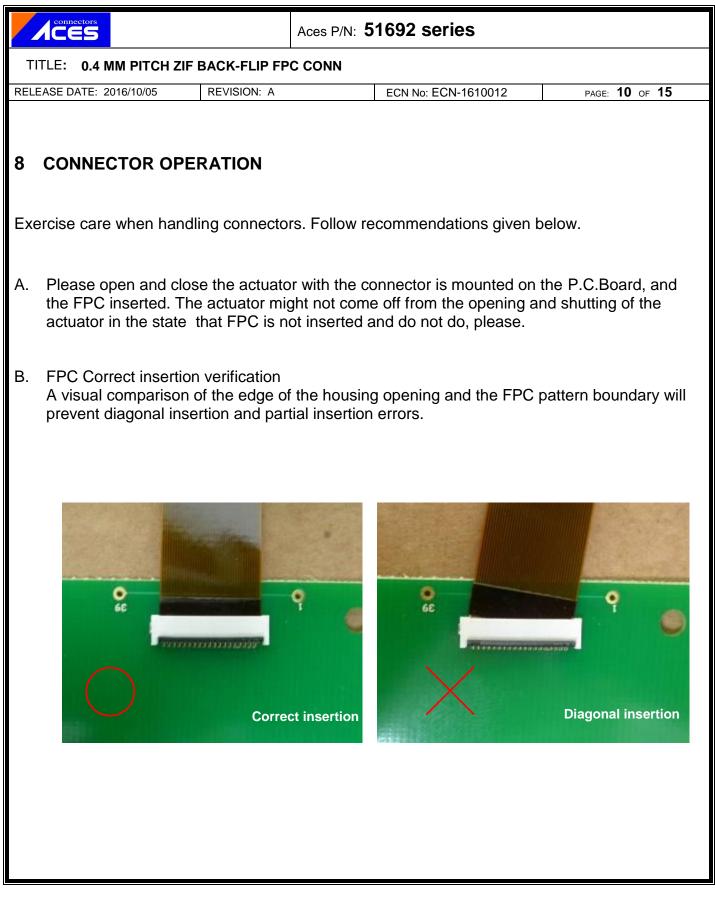
|--|

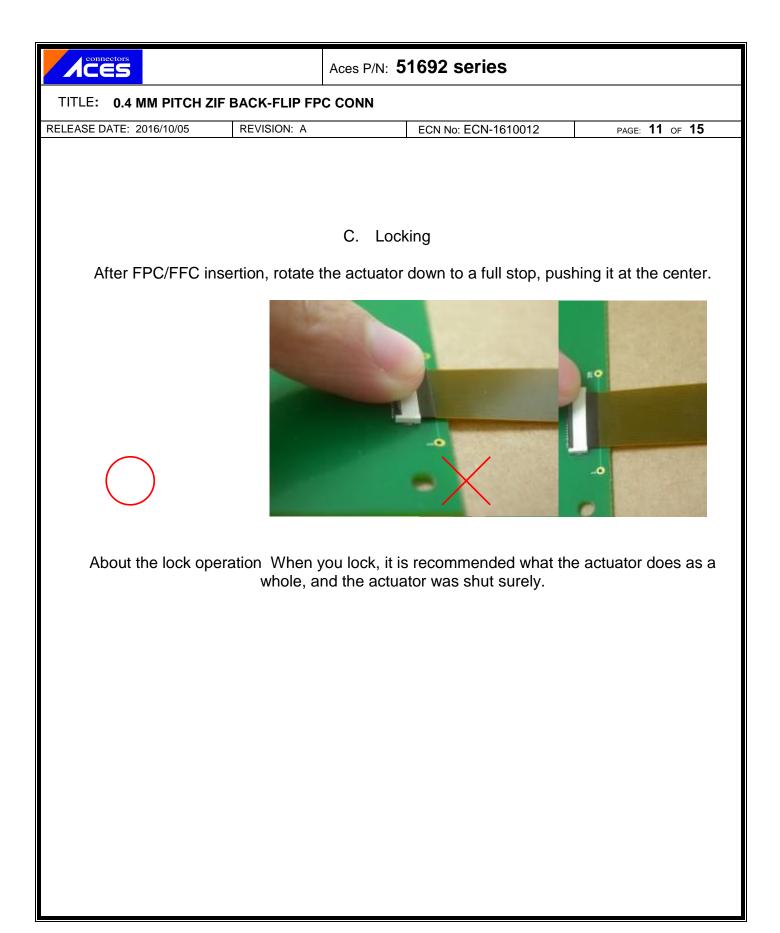
REVISION: A

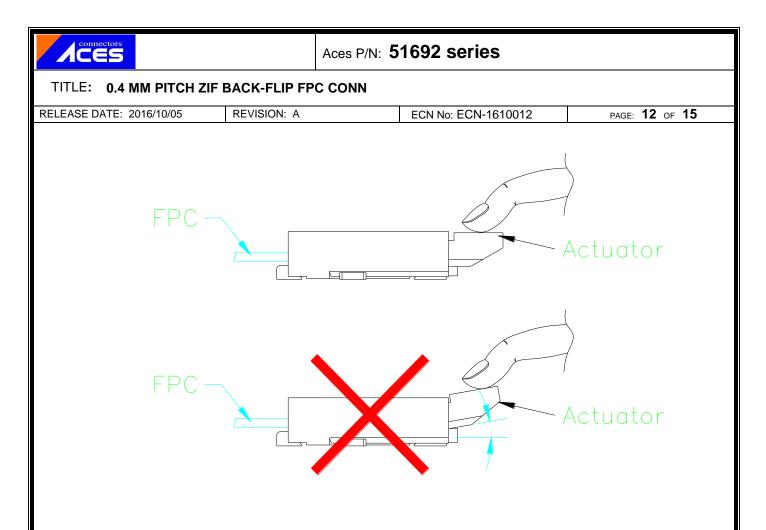
ECN No: ECN-1610012

### 7 PRODUCT QUALIFICATION AND TEST SEQUENCE

	Test Group									
Test or Examination	1	2	3	4	5	6	7	8	9	10
				Т	est Se	quenc	e			
Examination of Product				1、7	1、6	1、4		1	1	1
Low Level Contact Resistance		1、5	1、4	2、10	2、9	2、5			3	
Insulation Resistance				3、9	3、8					
Dielectric Withstanding Voltage				4 • 8	4 • 7					
Temperature rise	1									
Durability		3								
Vibration			2							
Shock (Mechanical)			3							
Thermal Shock				5						
Humidity				6						
Temperature life					5					
Salt Spray(Only For Gold Plating)						3				
Solder ability							1			
FPC Retention Force		2、4								
Terminal / Housing Retention Force										2
Fitting Nail /Housing Retention Force										3
Resistance to Soldering Heat									2	
Hand Soldering Temperature Resistance								2		
Sample Size	2	4	4	4	4	4	2	4	4	4







D. Lock release

Carefully rotate the actuator up to 90°, lifting it at the center.

